

| Type number | Package | Package description | Total product weight |
|-------------|----------|---------------------|----------------------|
| 74HCT86PW | SOT402-1 | TSSOP14 | 56.25859 mg |

| 12NC | Version | Pb-free soldering | | | Pb soldering | | | Number of processing cycles | Assembly site | RHF-indicator |
|--------------|---------|-------------------|-----|------|--------------|-----|------|-----------------------------|---|---------------|
| | | MSL | PPT | MPPT | MSL | PPT | MPPT | | | |
| 935185850118 | 11 | 1 | 260 | 30 s | 1 | 240 | 20 s | 3 | Bangkok, Thailand; Nijmegen, Netherlands; Suzhou, China | |

| Subpart | Material group | Substances | CAS number | Mass(mg) | Mass(%) of subpart | Mass(%) of total product |
|---------------------|------------------|--|-------------|----------|--------------------|--------------------------|
| Adhesive | Filler | Silver (Ag) | 7440-22-4 | 0.51264 | 80.10000 | 0.91122 |
| | Polymer | Resin system | Proprietary | 0.12736 | 19.90000 | 0.22638 |
| | | subTotal | | 0.64000 | 100.00000 | 1.13760 |
| Die | Doped silicon | Silicon (Si) | 7440-21-3 | 0.27990 | 100.00000 | 0.49752 |
| | | subTotal | | 0.27990 | 100.00000 | 0.49752 |
| Lead Frame Material | Copper alloy | Copper (Cu) | 7440-50-8 | 20.46870 | 97.47000 | 36.38324 |
| | | Iron (Fe) | 7439-89-6 | 0.50400 | 2.40000 | 0.89586 |
| | | Phosphorous (P) | 7723-14-0 | 0.00630 | 0.03000 | 0.01120 |
| | | Zinc (Zn) | 7440-66-6 | 0.02100 | 0.10000 | 0.03733 |
| | | subTotal | | 21.00000 | 100.00000 | 37.32763 |
| Mould Compound | Additive | Non hazardous | Proprietary | 1.59330 | 4.70000 | 2.83210 |
| | Filler | Silica fused | 60676-86-0 | 26.78100 | 79.00000 | 47.60340 |
| | Flame retardant | Magnesium Hydroxide (Mg(OH)2) | 1309-42-8 | 2.03400 | 6.00000 | 3.61545 |
| | Pigment | Carbon black | 1333-86-4 | 0.06780 | 0.20000 | 0.12051 |
| | Polymer | 1,4-bis(methoxymethyl)benzene/phenol copolymer | 26834-02-6 | 1.35600 | 4.00000 | 2.41030 |
| | | Non hazardous | Proprietary | 1.38990 | 4.10000 | 2.47056 |
| | | Tetramethylbiphenyl diglycidyl ether | 85954-11-6 | 0.67800 | 2.00000 | 1.20515 |
| | | subTotal | | 33.90000 | 100.00000 | 60.25747 |
| Pre-Plating | Pure metal layer | Gold (Au) | 7440-57-5 | 0.00350 | 1.00000 | 0.00622 |
| | | Nickel (Ni) - cas no. 7440-02-0 | 7440-02-0 | 0.33950 | 97.00000 | 0.60346 |
| | | Palladium (Pd) | 7440-05-3 | 0.00700 | 2.00000 | 0.01244 |
| | | subTotal | | 0.35000 | 100.00000 | 0.62212 |
| Wire | Pure metal | Copper (Cu) | 7440-50-8 | 0.08870 | 100.00000 | 0.15766 |
| | | subTotal | | 0.08870 | 100.00000 | 0.15766 |

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